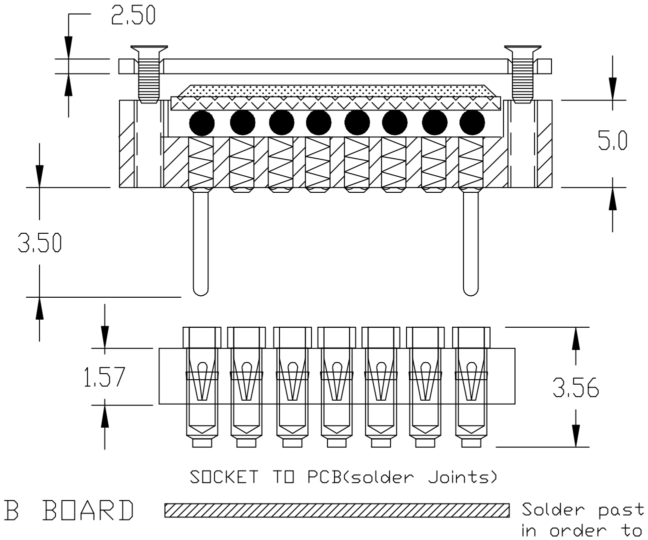
ECN NO.	REV.	DESCRIPTION OF CHANGE	EFFECTIVE DATE	ORIGINATOR
990138	0	initial	4/30/99	Ray Kuang

ASSEMBLY FLOW
↓
Retention Frame
↓
BGA PACAKGE
↓
BGA SOCKET
SE-BG329-A
↓
BGA ADAPTER SOCKET
(see Sm-BG329-B)
↓
PCB BOARD



Solder past thickness need to be at least 0.20mm(or0.008 inch)
in order to have reliable solder joint

Please see detail drawing for part number

Note: Dim: mm

1. To remove BGA socket from adapter socket,
Use removal tool from Mill-Max

2. Mill-Max phone: 516-922-6000

ACTEL CONFIDENTIAL

UNLESS OTHERWISE SPECIFIED
DIMENSIONS ARE IN MILLIMETERS
DECIMAL ANGULAR
X.X ±0.10 ±1°
X.XX ±0.05
X.XXX ±0.03
MATERIAL SEE NOTES
FINISH SEE NOTES
DO NOT SCALE DRAWING

PROJECTION

APPROVALS		DATE
DRAWN	Ray Kuang	4/27/99
CHECKED		
ENG'R		
RELEASED		

ACTEL CORP SUNNYVALE CA 94086
955 E ARQUES AVE
Actel

TITLE
TITLE
329-31x31mm, 1.27mm E-TEC BGA SOCKET
(329 BGA E-TEC Socket Assembly)

VENDOR NAME: e-tec
ACTEL DWG. NUMBER 1-07-09037
REV 0
SIZE B
VENDOR SID(PART) NUMBER
VENDOR DWG. NUMBER
REV
Actel Part#:
SCALE: NONE
SHEET 2 OF 2